

5555 NE Moore Ct.

Hillsboro OR 97124

Solder Balls

Substrate

Foil

Solder Mask

22.12%

16.39%

2.03%

4.18%

0.140

0.1039

0.0129

0.0265

21.35%

0.66%

0.11%

5.24%

11.15%

2.03%

0.98%

1.60%

0.61%

0.61%

0.37%

0.135

0.004

0.001

0.033

0.071

0.013

0.006

0.010

0.004

0.004

0.002

Device Material Content

Assembly: ASEK

Size (mm): 14 x 14

SAC305

BT Resin CCL-HL832NX-A

Solder mask PSR4000 AUS 320

96.50%

3.00%

0.50%

32.00%

68.00%

100.00%

23.52%

38.20%

14.70%

14.70%

8.88%

7440-31-5

7440-22-4

7440-50-8

65997-17-3

7440-50-8

64742-94-5

14807-96-6

85954-11-6

7727-43-7

custreg@latticesemi.com 256 caBGA BG256 Lead pitch (mm): 0.8 Package: **Total Device Weight** 0.634 Milligrams **Products:** MSL: 3 XO3L/LF-9400 Reflow max (°C): 260 May, 2022 % of Total % of Total Weight (g) Weight (g) Substance CAS# % of Subst. Notes / Assumptions: Pkg. Wt. Pkg. Wt. 1.89% 0.012 Die Die size: 5.092 x 4.968 mm 1.89% 0.012 Silicon chip 7440-21-3 100.00% Mold Compound 52.42% 0.332 Kyocera KE-G1250AHT (ULA) 45.87% 0.291 Silica 60676-86-0 87.50% 3.41% 0.022 Epoxy resin 6.50% 2.88% 0.018 Phenol Resin 5.50% 1333-86-4 0.50% 0.26% 0.002 Carbon Black 0.68% 0.004 D/A Epoxy Die attach epoxy: Henkel (Ablebond) 2100A 0.54% 0.003 7440-22-4 Silver 80.00% 0.14% 0.001 20.00% Epoxy Resin Wire 0.28% 0.002 CuPdAu+ 0.002 7440-50-8 96.55% 0.27% Copper 0.01% 0.000 Palladium 7440-05-3 3.10% 0.00% 0.000 Gold 7440-57-5 0.35%

Tin (Sn)

Silver (Ag)

Copper (Cu)

BT Resins

Glass fiber

Copper

Solvent naphtha (petroleum)

Phosphinoxide derivative

Epoxy Resin

Barium Sulfate

Talc (containing no asbestiform fibers)

Package Code:

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PCN#09A-19